



**SPECIFICATION CHANGES FOR S/N 09/586,518**

The following patent documents are related to the present invention and are hereby incorporated by reference in their entirety; these U.S. Patent Applications are identified by their Serial Nos. as follows: 09/034,546, filed on [ ] March 3, 1998 and entitled "Thermally-induced Voltage Alteration (TIVA)", now U.S. Patent No. 6,078,183; and [09/ \_\_, \_\_] 09/586,505, entitled "Method and Apparatus for Analyzing Functional Failures In Integrated Circuits" (Docket No. SD6542S93805) and [09/ \_\_, \_\_] 09/586,572, entitled "Data Processing Device Test Apparatus and Method Therefor" (Docket No.184-P017US), which have been concurrently filed herewith.

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